

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S30	2	"US 20060175630"	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2008/02/14 17:27
S32	376	S31 and (cavity with (mold\$3))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 17:58
S31	6433	(257/720,705,706,707,712,796).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/02/14 17:58
S33	57	S31 and (cavity with (mold\$3) with fille\$1)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 17:59
S34	33	S33 and (heat near sink)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 18:01
S35	1	S31 and (cavity with (mold\$3) with filler)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 18:06
S36	17	S31 and (cavity with (mold\$3)) and (mold\$3 with filler)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 18:07
S37	1693	S31 and parallel	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 18:34
S38	712	S31 and (((integrated near circuit\$2) ic chip die dice semiconductor) with parallel)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 18:35

S39	16	S38 and (((integrated near circuit\$2) ic chip die dice semiconductor) with back-to-back)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 18:36
S40	9	(ceramic near board) same (aluminum with via)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 18:58
S43	53	(ceramic near board) same (copper with vias)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 19:00
S42	53	(ceramic near board) same (copper with via)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 19:00
S41	770	(ceramic near board) same (copperwith via)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 19:00
S44	90	(ceramic near board) same (copper with (hole throughhole))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 19:06
S45	525	(ceramic near board) and (copper with (vias hole throughhole))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 19:08
S46	17	S45 and S31	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 19:09
S47	2	"20040016568".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 19:14
S48	179	S45 and (copper with (heat thermal))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 19:16

S49	27	(US-20040008459-\$ or US-20010014029-\$ or US-20060175630-\$ or US-20030164549-\$). did. or (US-6656770-\$ or US-6020597-\$ or US-5844311-\$ or US-5920120-\$ or US-5886408-\$ or US-4985805-\$ or US-6281573-\$ or US-5977568-\$ or US-6147400-\$ or US-5912803-\$ or US-5587882-\$ or US-5523586-\$ or US-5268814-\$ or US-5155661-\$ or US-4609937-\$ or US-5014777-\$ or US-5089936-\$ or US-7250674-\$ or US-6437240-\$ or US-6858892-\$ or US-5177670-\$).did. or (US-3443168-\$ or US-3551758-\$).did.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/14 19:57
S50	27	(US-20040008459-\$ or US-20010014029-\$ or US-20060175630-\$ or US-20030164549-\$). did. or (US-6656770-\$ or US-6020597-\$ or US-5844311-\$ or US-5920120-\$ or US-5886408-\$ or US-4985805-\$ or US-6281573-\$ or US-5977568-\$ or US-6147400-\$ or US-5912803-\$ or US-5587882-\$ or US-5523586-\$ or US-5268814-\$ or US-5155661-\$ or US-4609937-\$ or US-5014777-\$ or US-5089936-\$ or US-7250674-\$ or US-6437240-\$ or US-6858892-\$ or US-5177670-\$).did. or (US-3443168-\$ or US-3551758-\$).did.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/14 19:59
S51	2	S50 and (back-to-back)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 20:01
S52	6	"756340".ap.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 20:18
S53	6	"314139".ap.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 20:19

2/ 15/ 2008 2:09:16 PM

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